pSEMI MATERIAL DECLARATION FORM

Product:	**PE43650**
Ordering Codes:	**PE43650A-Z**
Description:	**UltraCMOS® 50 Ω RF Digital Attenuator 5-bit, 15.5 dB, 9 kHz - 6 GHz**
Package:	**24L 4x4 QFN**
Environmental Compliance	EU **RoHS** Directive 2011/65/EC, **REACH** - EU ECHA SVHC, **Arsenic Free**, **JIG 101** - EIA/EICTA/JEITA, **Halogen Free** - IEC61249-2-21, **PFOS Free** - 2006/122/EC, **Antimony Trioxide Free**
Lead Finish	**NiPdAu**
Availability	**Now**

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	2.020438	5.05%	50,451.08
Die	Aluminum	7429-90-5	0.006146	0.02%	153.46
Die	Silicon	7440-21-3	0.000410	0.00%	10.23
Die	Arsenic	7440-38-2	0.000002	0.00%	0.05
Die	Boron	7440-42-8	0.000002	0.00%	0.05
Die	Phosphorus	7723-14-0	0.000008	0.00%	0.20
Die	Titanium	7440-32-6	0.001024	0.00%	25.58
Die	Tungsten	7440-33-7	0.020486	0.05%	511.54
Die	Cobalt	7440-48-4	0.000041	0.00%	1.02
Die	Copper	7440-50-8	0.000016	0.00%	0.41
Leadframe	Copper	7440-50-8	18.336300	45.79%	457,864.09
Leadframe	Iron	7439-89-6	0.432500	1.08%	10,799.68
Leadframe	Zinc	7440-66-6	0.028200	0.07%	704.16
Leadframe	Phosphorus	7723-14-0	0.005600	0.01%	139.83
Plating	Nickel	7440-02-0	0.124900	0.31%	3,118.80
Plating	Palladium	7440-05-3	0.010200	0.03%	254.70
Plating	Gold	7440-57-5	0.000400	0.00%	9.99
Wire	Gold	7440-57-5	0.440600	1.10%	11,001.94
Die Attach	Silver	7440-22-4	0.166800	0.42%	4,165.06
Die Attach	Epoxy Resin	9003-36-5	0.020900	0.05%	521.88
Die Attach	Diluent	26447-14-3	0.012500	0.03%	312.13
Die Attach	Dicyandiamide	461-58-5	0.002100	0.01%	52.44
Die Attach	Hardener	620-92-8	0.006300	0.02%	157.31
Molding Compound	Silica Fused	60676-86-0	16.883400	42.16%	421,584.65
Molding Compound	Epoxy Resin	Trade Secret	0.736500	1.84%	18,390.67
Molding Compound	Phenol Resin	Trade Secret	0.736500	1.84%	18,390.67
Molding Compound	Carbon Black	1333-86-4	0.055200	0.14%	1,378.36
Total Weight (mg)			**40.047474**	100.00%	1,000,000